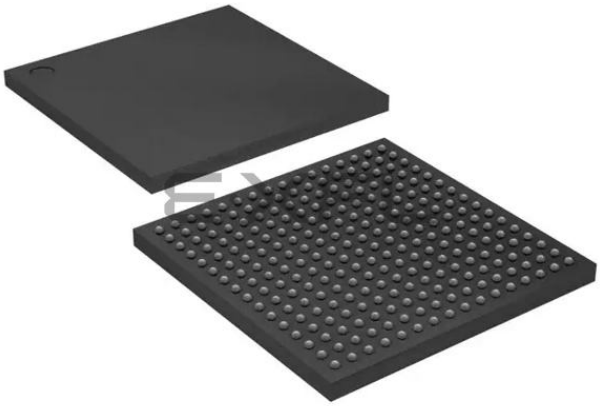

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Details	
Product Status	Active
Number of LABs/CLBs	516
Number of Logic Elements/Cells	8256
Total RAM Bits	165888
Number of I/O	182
Number of Gates	-
Voltage - Supply	1.15V ~ 1.25V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	256-LBGA
Supplier Device Package	256-FBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep2c8f256i8n

1. Introduction

CII51001-3.2

Introduction

Following the immensely successful first-generation Cyclone® device family, Altera® Cyclone II FPGAs extend the low-cost FPGA density range to 68,416 logic elements (LEs) and provide up to 622 usable I/O pins and up to 1.1 Mbits of embedded memory. Cyclone II FPGAs are manufactured on 300-mm wafers using TSMC's 90-nm low-k dielectric process to ensure rapid availability and low cost. By minimizing silicon area, Cyclone II devices can support complex digital systems on a single chip at a cost that rivals that of ASICs. Unlike other FPGA vendors who compromise power consumption and performance for low-cost, Altera's latest generation of low-cost FPGAs—Cyclone II FPGAs, offer 60% higher performance and half the power consumption of competing 90-nm FPGAs. The low cost and optimized feature set of Cyclone II FPGAs make them ideal solutions for a wide array of automotive, consumer, communications, video processing, test and measurement, and other end-market solutions. Reference designs, system diagrams, and IP, found at www.altera.com, are available to help you rapidly develop complete end-market solutions using Cyclone II FPGAs.

Low-Cost Embedded Processing Solutions

Cyclone II devices support the Nios II embedded processor which allows you to implement custom-fit embedded processing solutions. Cyclone II devices can also expand the peripheral set, memory, I/O, or performance of embedded processors. Single or multiple Nios II embedded processors can be designed into a Cyclone II device to provide additional co-processing power or even replace existing embedded processors in your system. Using Cyclone II and Nios II together allow for low-cost, high-performance embedded processing solutions, which allow you to extend your product's life cycle and improve time to market over standard product solutions.

Low-Cost DSP Solutions

Use Cyclone II FPGAs alone or as DSP co-processors to improve price-to-performance ratios for digital signal processing (DSP) applications. You can implement high-performance yet low-cost DSP systems with the following Cyclone II features and design support:

- Up to 150 18 × 18 multipliers
- Up to 1.1 Mbit of on-chip embedded memory
- High-speed interfaces to external memory

Dedicated Clock Pins

Larger Cyclone II devices (EP2C15 and larger devices) have 16 dedicated clock pins (CLK[15..0], four pins on each side of the device). Smaller Cyclone II devices (EP2C5 and EP2C8 devices) have eight dedicated clock pins (CLK[7..0], four pins on left and right sides of the device). These CLK pins drive the global clock network (GCLK), as shown in Figures 2–11 and 2–12.

If the dedicated clock pins are not used to feed the global clock networks, they can be used as general-purpose input pins to feed the logic array using the MultiTrack interconnect. However, if they are used as general-purpose input pins, they do not have support for an I/O register and must use LE-based registers in place of an I/O register.

Dual-Purpose Clock Pins

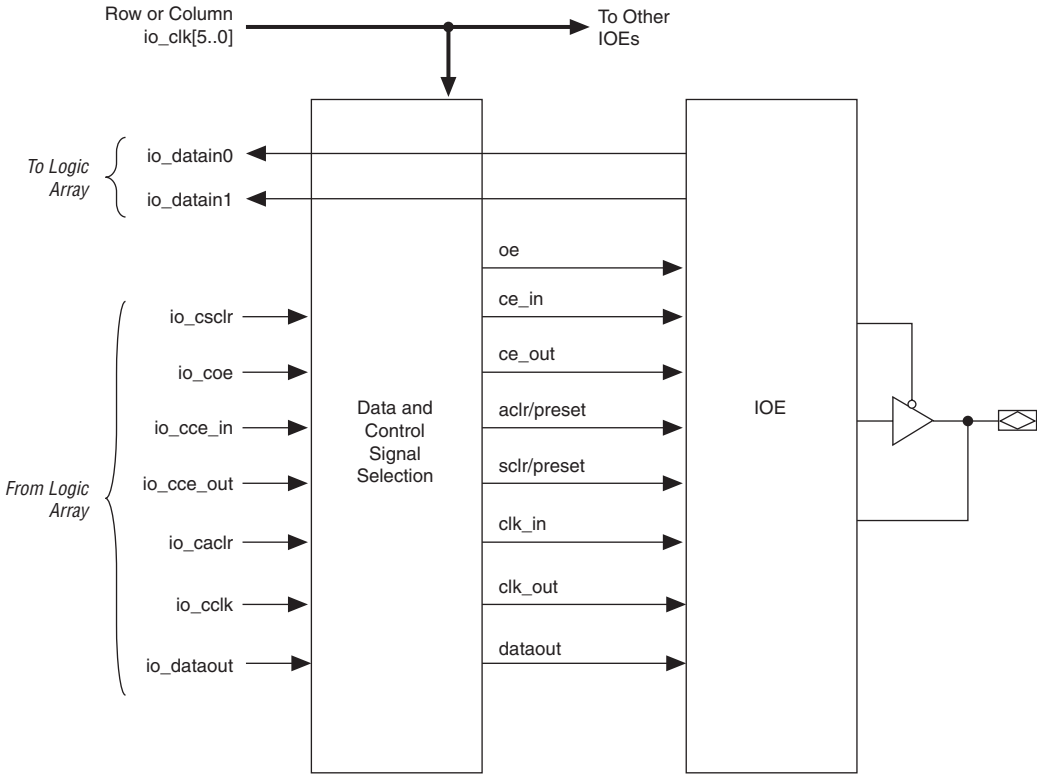
Cyclone II devices have either 20 dual-purpose clock pins, DPCLK[19..0] or 8 dual-purpose clock pins, DPCLK[7..0]. In the larger Cyclone II devices (EP2C15 devices and higher), there are 20 DPCLK pins; four on the left and right sides and six on the top and bottom of the device. The corner CDPCLK pins are first multiplexed before they drive into the clock control block. Since the signals pass through a multiplexer before feeding the clock control block, these signals incur more delay to the clock control block than other DPCLK pins that directly feed the clock control block. In the smaller Cyclone II devices (EP2C5 and EP2C8 devices), there are eight DPCLK pins; two on each side of the device (see Figures 2–11 and 2–12).

A programmable delay chain is available from the DPCLK pin to its fan-out destinations. To set the propagation delay from the DPCLK pin to its fan-out destinations, use the **Input Delay from Dual-Purpose Clock Pin to Fan-Out Destinations** assignment in the Quartus II software.

These dual-purpose pins can connect to the global clock network for high-fanout control signals such as clocks, asynchronous clears, presets, and clock enables, or protocol control signals such as TRDY and IRDY for PCI, or DQS signals for external memory interfaces.

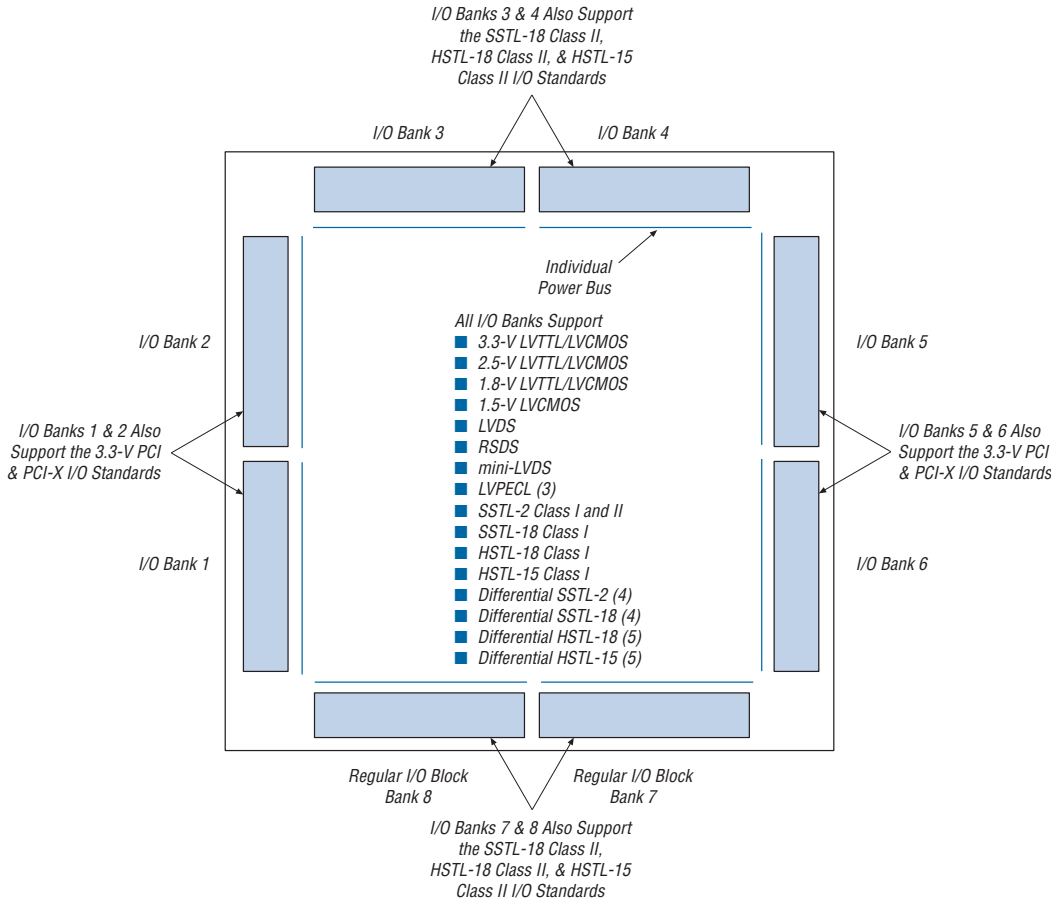
The pin's datain signals can drive the logic array. The logic array drives the control and data signals, providing a flexible routing resource. The row or column IOE clocks, io_clk[5..0], provide a dedicated routing resource for low-skew, high-speed clocks. The global clock network generates the IOE clocks that feed the row or column I/O regions (see "Global Clock Network & Phase-Locked Loops" on page 2–16). Figure 2–23 illustrates the signal paths through the I/O block.

Figure 2–23. Signal Path Through the I/O Block



Each IOE contains its own control signal selection for the following control signals: oe, ce_in, ce_out, aclr/preset, sclr/preset, clk_in, and clk_out. Figure 2–24 illustrates the control signal selection.

Figure 2–29. EP2C15, EP2C20, EP2C35, EP2C50 & EP2C70 I/O Banks *Notes (1), (2)*



Notes to Figure 2–29:

(1) This is a top view of the silicon die.
(2) This is a graphic representation only. Refer to the pin list and the Quartus II software for exact pin locations.
(3) The LVPECL I/O standard is only supported on clock input pins. This I/O standard is not supported on output pins.
(4) The differential SSTL-18 and SSTL-2 I/O standards are only supported on clock input pins and PLL output clock pins.
(5) The differential 1.8-V and 1.5-V HSTL I/O standards are only supported on clock input pins and PLL output clock pins.

Each I/O bank has its own VCCIO pins. A single device can support 1.5-V, 1.8-V, 2.5-V, and 3.3-V interfaces; each individual bank can support a different standard with different I/O voltages. Each bank also has dual-purpose VREF pins to support any one of the voltage-referenced

Devices Can Be Driven before Power-Up

You can drive signals into the I/O pins, dedicated input pins, and dedicated clock pins of Cyclone II devices before or during power-up or power-down without damaging the device. Cyclone II devices support any power-up or power-down sequence (V_{CCIO} and V_{CCINT}) to simplify system level design.

I/O Pins Remain Tri-Stated during Power-Up

A device that does not support hot socketing may interrupt system operation or cause contention by driving out before or during power-up. In a hot-socketing situation, the Cyclone II device's output buffers are turned off during system power-up or power-down. The Cyclone II device also does not drive out until the device is configured and has attained proper operating conditions. The I/O pins are tri-stated until the device enters user mode with a weak pull-up resistor (R) to 3.3V. Refer to Figure 4–1 for more information.

You can power up or power down the V_{CCIO} and V_{CCINT} pins in any sequence. The V_{CCIO} and V_{CCINT} must have monotonic rise to their steady state levels. (Refer to Figure 4–3 for more information.) The power supply ramp rates can range from 100 µs to 100 ms for non "A" devices. Both V_{CC} supplies must power down within 100 ms of each other to prevent I/O pins from driving out. During hot socketing, the I/O pin capacitance is less than 15 pF and the clock pin capacitance is less than 20 pF. Cyclone II devices meet the following hot-socketing specification.

- The hot-socketing DC specification is $| I_{IOPIN} | < 300$ µA.
- The hot-socketing AC specification is $| I_{IOPIN} | < 8$ mA for 10 ns or less.

This specification takes into account the pin capacitance but not board trace and external loading capacitance. You must consider additional capacitance for trace, connector, and loading separately.

I_{IOPIN} is the current at any user I/O pin on the device. The DC specification applies when all V_{CC} supplies to the device are stable in the powered-up or powered-down conditions. For the AC specification, the peak current duration due to power-up transients is 10 ns or less.

A possible concern for semiconductor devices in general regarding hot socketing is the potential for latch-up. Latch-up can occur when electrical subsystems are hot socketed into an active system. During hot socketing, the signal pins may be connected and driven by the active system before

Table 5–42. Cyclone II I/O Output Delay for Column Pins (Part 5 of 6)

I/O Standard	Drive Strength	Parameter	Fast Corner		–6 Speed Grade	–7 Speed Grade (2)	–7 Speed Grade (3)	–8 Speed Grade	Unit
			Industrial/ Automotive	Commer -cial					
DIFFERENTIAL_ SSTL_18_CLASS_I	6 mA	t_{OP}	1472	1544	3140	3345	3542	3549	ps
		t_{DIP}	1604	1683	3310	3539	3768	3768	ps
	8 mA	t_{OP}	1469	1541	3086	3287	3482	3489	ps
		t_{DIP}	1601	1680	3256	3481	3708	3708	ps
	10 mA	t_{OP}	1466	1538	2980	3171	3354	3361	ps
		t_{DIP}	1598	1677	3150	3365	3580	3580	ps
	12 mA (1)	t_{OP}	1466	1538	2980	3171	3354	3361	ps
		t_{DIP}	1598	1677	3150	3365	3580	3580	ps
DIFFERENTIAL_ SSTL_18_CLASS_II	16 mA	t_{OP}	1454	1525	2905	3088	3263	3270	ps
		t_{DIP}	1586	1664	3075	3282	3489	3489	ps
	18 mA (1)	t_{OP}	1453	1524	2900	3082	3257	3264	ps
		t_{DIP}	1585	1663	3070	3276	3483	3483	ps
1.8V_DIFFERENTIAL _HSTL_CLASS_I	8 mA	t_{OP}	1460	1531	3222	3424	3618	3625	ps
		t_{DIP}	1592	1670	3392	3618	3844	3844	ps
	10 mA	t_{OP}	1462	1534	3090	3279	3462	3469	ps
		t_{DIP}	1594	1673	3260	3473	3688	3688	ps
	12 mA (1)	t_{OP}	1462	1534	3090	3279	3462	3469	ps
		t_{DIP}	1594	1673	3260	3473	3688	3688	ps
1.8V_DIFFERENTIAL _HSTL_CLASS_II	16 mA	t_{OP}	1449	1520	2936	3107	3271	3278	ps
		t_{DIP}	1581	1659	3106	3301	3497	3497	ps
	18 mA	t_{OP}	1450	1521	2924	3101	3272	3279	ps
		t_{DIP}	1582	1660	3094	3295	3498	3498	ps
	20 mA (1)	t_{OP}	1452	1523	2926	3096	3259	3266	ps
		t_{DIP}	1584	1662	3096	3290	3485	3485	ps
1.5V_DIFFERENTIAL _HSTL_CLASS_I	8 mA	t_{OP}	1779	1866	4292	4637	4974	4981	ps
		t_{DIP}	1911	2005	4462	4831	5200	5200	ps
	10 mA	t_{OP}	1784	1872	4031	4355	4673	4680	ps
		t_{DIP}	1916	2011	4201	4549	4899	4899	ps
	12 mA (1)	t_{OP}	1784	1872	4031	4355	4673	4680	ps
		t_{DIP}	1916	2011	4201	4549	4899	4899	ps

Table 5–45. Maximum Output Clock Toggle Rate on Cyclone II Devices (Part 4 of 4)

I/O Standard	Drive Strength	Maximum Output Clock Toggle Rate on Cyclone II Devices (MHz)								
		Column I/O Pins *(1)*			Row I/O Pins *(1)*			Dedicated Clock Outputs		
		–6 Speed Grade	–7 Speed Grade	–8 Speed Grade	–6 Speed Grade	–7 Speed Grade	–8 Speed Grade	–6 Speed Grade	–7 Speed Grade	–8 Speed Grade
1.5V_ DIFFERENTIAL_HSTL _CLASS_I	8 mA	210	170	140	210	170	140	210	170	140
	10 mA	220	180	150	—	—	—	—	—	—
	12 mA	230	190	160	—	—	—	—	—	—
1.5V_ DIFFERENTIAL_HSTL _CLASS_II	16 mA	210	170	140	—	—	—	—	—	—
LVDS	—	400	340	280	400	340	280	400	340	280
RSDS	—	400	340	280	400	340	280	400	340	280
MINI_LVDS	—	400	340	280	400	340	280	400	340	280
SIMPLE_RSDS	—	380	320	260	380	320	260	380	320	260
1.2V_HSTL	—	80	80	80	—	—	—	—	—	—
1.2V_ DIFFERENTIAL_HSTL	—	80	80	80	—	—	—	—	—	—
PCI	—	—	—	—	350	315	280	350	315	280
PCI-X	—	—	—	—	350	315	280	350	315	280
LVTTL	OCT_25_ OHMS	360	300	250	360	300	250	360	300	250
LVCMOS	OCT_25_ OHMS	360	300	250	360	300	250	360	300	250
2.5V	OCT_50_ OHMS	240	200	160	240	200	160	240	200	160
1.8V	OCT_50_ OHMS	290	240	200	290	240	200	290	240	200
SSTL_2_CLASS_I	OCT_50_ OHMS	240	200	160	240	200	160	—	—	—
SSTL_18_CLASS_I	OCT_50_ OHMS	290	240	200	290	240	200	—	—	—

Note to Table 5–45:
(1) This is based on single data rate I/Os.

Table 5–46. Maximum Output Clock Toggle Rate Derating Factors (Part 2 of 4)

I/O Standard	Drive Strength	Maximum Output Clock Toggle Rate Derating Factors (ps/pF)								
		Column I/O Pins			Row I/O Pins			Dedicated Clock Outputs		
		–6 Speed Grade	–7 Speed Grade	–8 Speed Grade	–6 Speed Grade	–7 Speed Grade	–8 Speed Grade	–6 Speed Grade	–7 Speed Grade	–8 Speed Grade
SSTL_2_CLASS_II	16 mA	42	43	45	15	29	42	15	29	42
	20 mA	41	42	44	—	—	—	—	—	—
	24 mA	40	42	43	—	—	—	—	—	—
SSTL_18_ CLASS_I	6 mA	20	22	24	46	47	49	46	47	49
	8 mA	20	22	24	47	49	51	47	49	51
	10 mA	20	22	25	23	25	27	23	25	27
	12 mA	19	23	26	—	—	—	—	—	—
SSTL_18_ CLASS_II	16 mA	30	33	36	—	—	—	—	—	—
	18 mA	29	29	29	—	—	—	—	—	—
1.8V_HSTL_ CLASS_I	8 mA	26	28	29	59	61	63	59	61	63
	10 mA	46	47	48	65	66	68	65	66	68
	12 mA	67	67	67	71	71	72	71	71	72
1.8V_HSTL_ CLASS_II	16 mA	62	65	68	—	—	—	—	—	—
	18 mA	59	62	65	—	—	—	—	—	—
	20 mA	57	59	62	—	—	—	—	—	—
1.5V_HSTL_ CLASS_I	8 mA	40	40	41	28	32	36	28	32	36
	10 mA	41	42	42	—	—	—	—	—	—
	12 mA	43	43	43	—	—	—	—	—	—
1.5V_HSTL_ CLASS_II	16 mA	18	20	21	—	—	—	—	—	—
DIFFERENTIAL_SSTL_2 _CLASS_I	8 mA	46	47	49	25	40	56	25	40	56
	12 mA	67	69	70	23	42	60	23	42	60
DIFFERENTIAL_SSTL_2 _CLASS_II	16 mA	42	43	45	15	29	42	15	29	42
	20 mA	41	42	44	—	—	—	—	—	—
	24 mA	40	42	43	—	—	—	—	—	—
DIFFERENTIAL_SSTL_ 18_CLASS_I	6 mA	20	22	24	46	47	49	46	47	49
	8 mA	20	22	24	47	49	51	47	49	51
	10 mA	20	22	25	23	25	27	23	25	27
	12 mA	19	23	26	—	—	—	—	—	—

Tables 7–4 and 7–5 describe the Cyclone II PLL input and output ports.

Table 7–4. PLL Input Signals

Port	Description	Source	Destination
inclk[1..0]	Primary and secondary clock inputs to the PLL.	Dedicated clock input pins	*n* counter
pllena	pllena is an active high signal that acts as an enable and reset signal for the PLL. It can be used for enabling or disabling each PLL. When pllena transitions low, the PLL clock output ports are driven to GND and the PLL loses lock. Once pllena transitions high again, the lock process begins and the PLL re-synchronizes to its input reference clock. The pllena port can be driven by an LE output or any general-purpose I/O pin.	Logic array or input pin	PLL control signal
areset	areset is an active high signal that resets all PLL counters to their initial values. When this signal is driven high the PLL resets its counters, clears the PLL outputs and loses lock. Once this signal is driven low again, the lock process begins and the PLL re-synchronizes to its input reference clock. The areset port can be driven by an LE output or any general-purpose I/O pin.	Logic array or input pin	PLL control signal
pfdena	pfdena is an active high signal that enables or disables the up/down output signals from the PFD. When pfdena is driven low, the PFD is disabled, while the VCO continues to operate. The PLL clock outputs continue to toggle regardless of the input clock, but may experience some long-term drift. Because the output clock frequency does not change for some time, you can use the pfdena port as a shutdown or cleanup function when a reliable input clock is no longer available. The pfdena port can be driven by an LE output or any general-purpose I/O pin.	Logic array or input pin	PFD
clkswitch	clkswitch is an active high switchover signal used to initiate manual clock switchover.	Logic array or input pin	PLL control signal

Table 7–6. I/O Standards Supported for Cyclone II PLLs (Part 2 of 2)

I/O Standard	Input	Output	
	inclk	lock	pll_out
SSTL-25 class II	✓	✓	✓
RSDS/mini-LVDS *(4)*		✓	✓

Notes to Table 7–6:
(1) The PCI-X I/O standard is supported only on side I/O pins.
(2) Differential SSTL and HSTL outputs are only supported on the PLL<#>_OUT pins.
(3) These I/O standards are only supported on top and bottom I/O pins.
(4) The RSDS and mini-LVDS pins are only supported on output pins.

Clock Feedback Modes

Cyclone II PLLs support four clock feedback modes: normal mode, zero delay buffer mode, no compensation mode, and source synchronous mode. Cyclone II PLLs do not have support for external feedback mode. All the supported clock feedback modes allow for multiplication and division, phase shifting, and programmable duty cycle. The phase relationships shown in the waveforms in Figures 7–4 through 7–6 are for the default (zero degree) phase shift setting. Changing the phase-shift setting changes the relationships between the output clocks from the PLL.

Normal Mode

In normal mode, the PLL phase-aligns the input reference clock with the clock signal at the ports of the registers in the logic array I/O registers to compensate for the internal global clock network delay. Use the `altpll` megafunction in the Quartus II software to define which internal clock output from the PLL (c0, c1, or c2) to compensate for.

If an external clock output pin (PLL<#>_OUT) is used in this mode, there is a phase shift with respect to the clock input pin. Similarly, if the internal PLL clock outputs are used to drive general-purpose I/O pins, there is be phase shift with respect to the clock input pin.

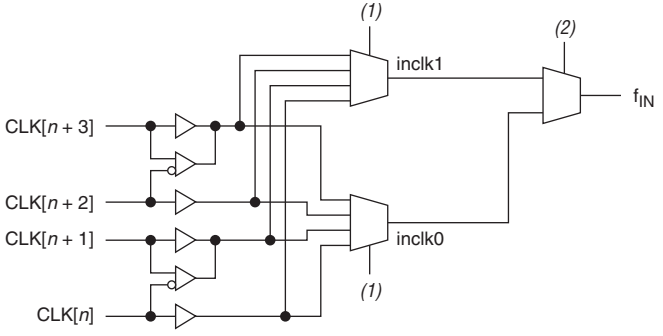
Figure 7–4 shows an example waveform of the PLL clocks' phase relationship in this mode.

Manual Clock Switchover

The Cyclone II PLLs support manual switchover of the reference clock through internal logic. This enables you to switch between two reference input clocks. Use this feature for a dual clock domain application such as in a system that turns on the redundant clock if the primary clock stops running.

Figure 7–10 shows how the PLL input clock (f_{IN}) is generated from one of four possible clock sources. The first stage multiplexing consists of two dedicated multiplexers that generate two single-ended or two differential clocks from four dedicated clock pins. These clock signals are then multiplexed to generate f_{IN} by using another dedicated 2-to-1 multiplexer. The first stage multiplexers are controlled by configuration bit settings in the configuration file generated by the Quartus II software, while the second stage multiplexer is either controlled by the configuration bit settings or logic array signal to allow the f_{IN} to be controlled dynamically. This allows the implementation of a manual clock switchover circuit where the PLL reference clock can be switched during user mode for applications that requires clock redundancy.

Figure 7–10. Cyclone II PLL Input Clock Generation

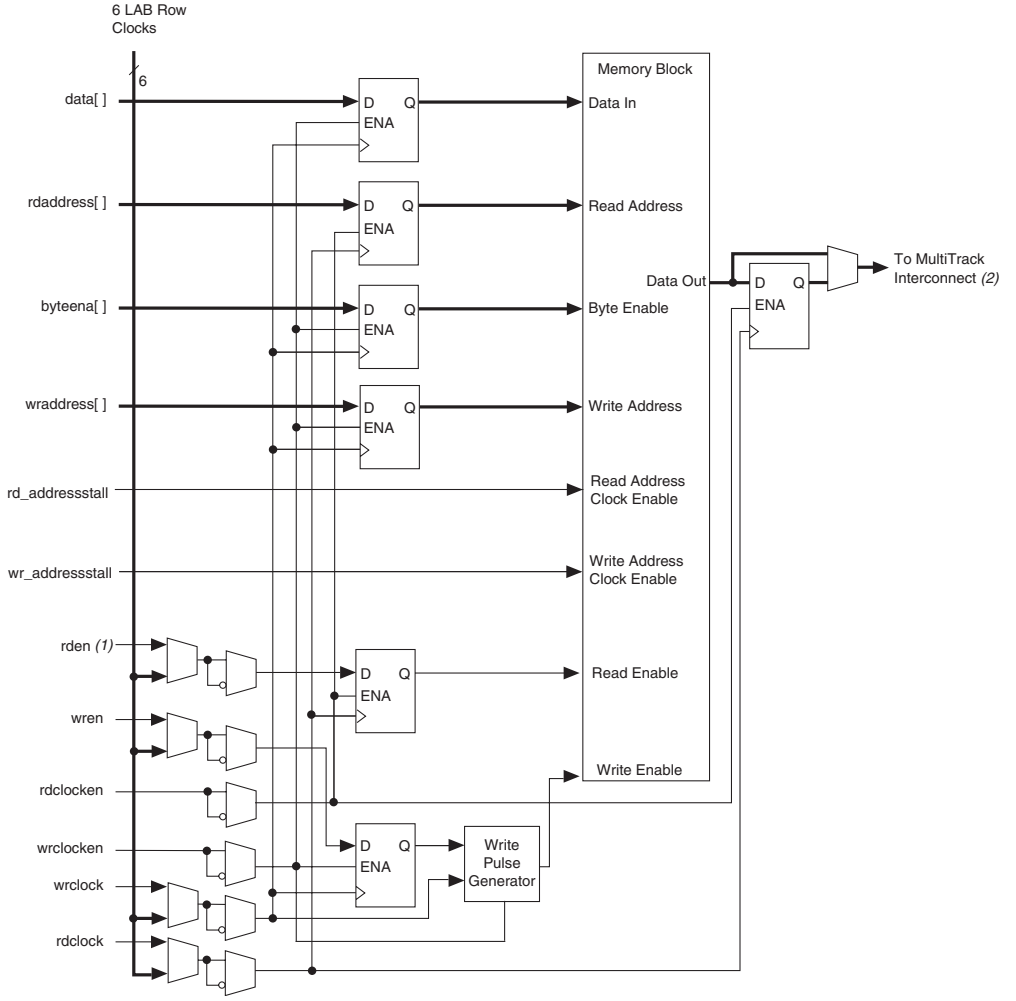


Notes to Figure 7–10:

(1) This select line is set through the configuration file.

(2) This select line can either be set through the configuration file or it can be dynamically set in user mode when using the manual switchover feature.

Figure 8–17. Cyclone II Read/Write Clock Mode *Notes (1), (2)*



Notes to Figure 8–17:

(1) Violating the setup or hold time on the memory block address registers could corrupt memory contents. This applies to both read and write operations.

(2) For more information about the MultiTract interconnect, refer to *Cyclone II Device Family Data Sheet* in volume 1 of the *Cyclone II Device Handbook*.

Single-Clock Mode

Cyclone II memory blocks support single-clock mode for true dual-port, simple dual-port, and single-port memory. In this mode, a single clock, together with a clock enable, controls all registers of the memory block. This mode does not support asynchronous clear signals for the registers. Figures 8–18 through 8–20 show the memory block in single-clock mode for true dual-port, simple dual-port, and single-port modes, respectively.

The DQS pins are listed in the Cyclone II pin tables as DQS[1..0]T, DQS[1..0]B, DQS[1..0]L, and DQS[1..0]R for the EP2C5 and EP2C8 devices and DQS[5..0]T, DQS[5..0]B, DQS[3..0]L, and DQS[3..0]R for the larger devices. The T denotes pins on the top of the device, the B denotes pins on the bottom of the device, the L denotes pins on the left of the device, and the R denotes pins on the right of the device. The corresponding DQ pins are marked as DQ[5..0]T[8..0], where [5..0] indicates which DQS group the pins belong to.

In the Cyclone II pinouts, the DQ groups with 9 DQ pins are also used in the ×8 mode with the corresponding DQS pins, leaving the unused DQ pin available as a regular I/O pin. The DQ groups that have 18 DQ pins are also used in the ×16 mode with the corresponding DQS pins, leaving the two unused DQ pins available as regular I/O pins. For example, DQ1T[8..0] can be used in the ×8 mode, provided it is used with DQS1T. The remaining unused DQ pin, DQ1T8, is available as a regular I/O pin.

When not used as DQ or DQS pins, these pins are available as regular I/O pins. Table 9–3 shows the number of DQS pins supported in each I/O bank in each Cyclone II device density.

Table 9–3. Available DQS Pins in Each I/O Bank & Each Device *Note (1)*

Device	Top I/O Bank	Bottom I/O Bank	Left I/O Bank	Right I/O Bank
EP2C5, EP2C8	DQS[1..0]T	DQS[1..0]B	DQS[1..0]L	DQS[1..0]R
EP2C15, EP2C20, EP2C35, EP2C50, EP2C70	DQS[5..0]B	DQS[5..0]T	DQS[3..0]L	DQS[3..0]R

Note to Table 9–3:
(1) Numbers are preliminary.

The DQ pin numbering is based on ×8/×9 mode. There are up to 8 DQS/DQ groups in ×8 mode or 4 DQS/DQ groups in ×9 mode in I/O banks for EP2C5 and EP2C8. For the larger devices, there are up to 20 DQS/DQ groups in ×8 mode or 8 DQS/DQ groups in ×9 mode. Although there are up to 20 DQS/DQ groups in the ×8 mode available in the larger Cyclone II devices, but because of the available clock resources in the Cyclone II devices, only 16 DQS/DQ groups can be utilized for the external memory interface. There is a total of 16 global clock buses available for routing DQS signals but 2 of them are needed for routing the –90° write clock and the system clock to the external memory devices. This reduces the global clock resources to 14 global clock buses for routing DQS signals. Incoming DQS signals are all routed to the clock control block, and are then routed to the global clock bus to clock the DDR LE registers. For EP2C5 and EP2C8 devices, the DQS signals are routed

Document Revision History

Table 9–4 shows the revision history for this document.

Table 9–4. Document Revision History

Date & Document Version	Changes Made	Summary of Changes
February 2007 v3.1	• Added document revision history. • Added handpara note in "Data & Data Strobe Pins" section. • Updated "DDR Output Registers" section.	• Elaboration of DDR2 and QDRII interfaces supported by I/O bank included.
November 2005, v2.1	• Introduction • Updated Table 9–2. • Updated Figure 9–7.	
July 2005, v2.0	Updated Table 9–2.	
November 2004, v1.1	• Moved the "External Memory Interface Standards" section to follow the "Introduction" section. • Updated the "Data & Data Strobe Pins" section. • Updated Figures 9–11, 9–12, 9–15, 9–16, and 9–17.	
June 2004, v1.0	Added document to the Cyclone II Device Handbook.	

Referenced Documents

This chapter references the following documents:

- *Altera Reliability Report*
- *AN 75: High-Speed Board Designs*
- *Cyclone II Architecture* chapter in volume 1 of the *Cyclone II Device Handbook*
- *Cyclone II Device Family Data Sheet*, *section 1* of the *Cyclone II Device Handbook*
- *DC Characteristics and Timing Specifications* chapter in volume 1 of the *Cyclone II Device Handbook*
- *External Memory Interfaces* chapter in volume 1 of the *Cyclone II Device Handbook*
- *High Speed Differential Interfaces in Cyclone II Devices* chapter in volume 1 of the *Cyclone II Device Handbook*
- *Hot Socketing & Power-On Reset* chapter in volume 1 of the *Cyclone II Device Handbook*
- *I/O Management* chapter in volume 2 of the *Quartus II Handbook*

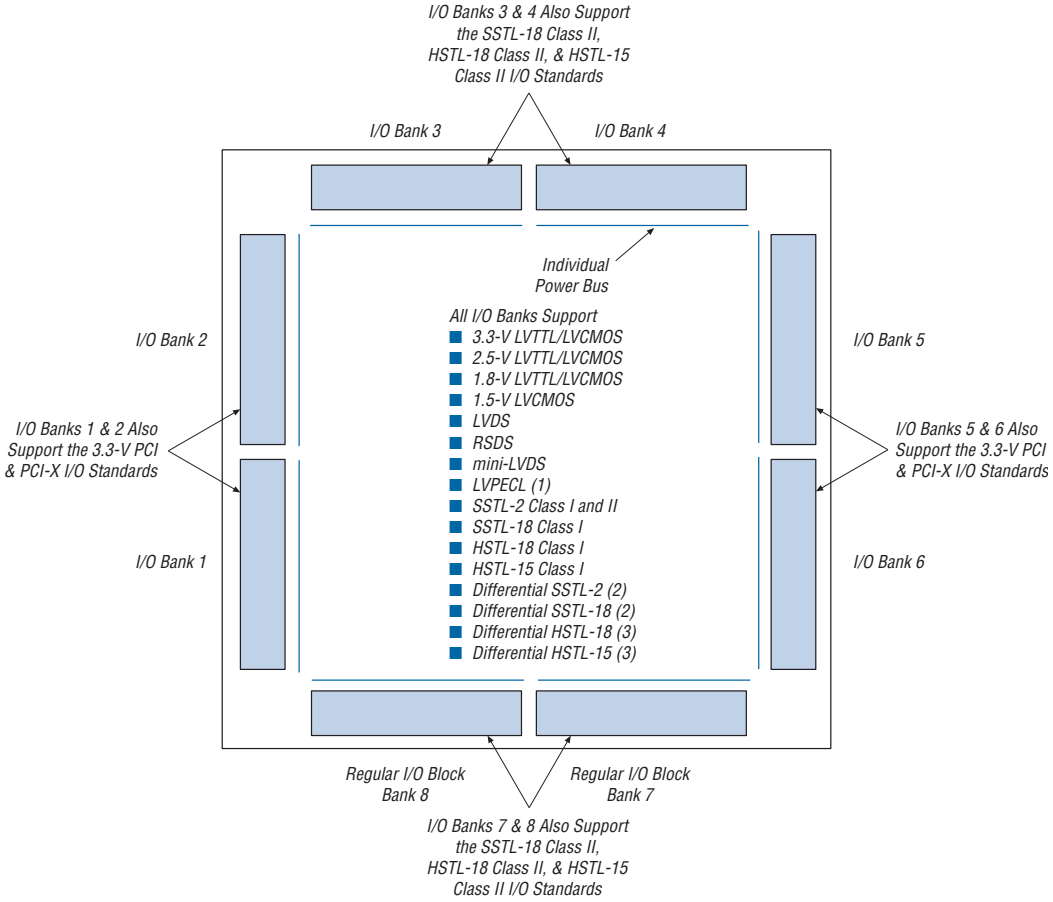
Document Revision History

Table 10–13 shows the revision history for this document.

Table 10–13. Document Revision History

Date and Document Version	Changes Made	Summary of Changes
February 2008 v2.4	• Added "Referenced Documents" section. • Updated "Differential Pad Placement Guidelines" section.	—
February 2007 v2.3	• Added document revision history. • Updated "Introduction" and its feetpara note. • Updated *Note (2)* in Table 10–4. • Updated "Differential LVPECL" section. • Updated "Differential Pad Placement Guidelines" section. • Updated "Output Pads" section. • Added new section "5.0-V Device Compatibility" with two new figures.	• Added reference detail for ESD specifications. • Added information about differential placement restrictions applying only to pins in the same bank. • Added information that Cyclone II device supports LVDS on clock inputs at 3.3V V_{CCIO}. • Added more information on DC placement guidelines. • Added information stating SSTL and HSTL outputs can be closer than 2 pads from V_{REF}. • Added 5.0 Device tolerence solution.

Figure 11–2. I/O Banks in EP2C15, EP2C20, EP2C35, EP2C50 & EP2C70 Devices



Notes to Figure 11–2:

(1) The LVPECL I/O standard is only supported on clock input pins. This I/O standard is not supported on output pins.

(2) The differential SSTL-18 and SSTL-2 I/O standards are only supported on clock input pins and PLL output clock pins.

(3) The differential 1.8-V and 1.5-V HSTL I/O standards are only supported on clock input pins and PLL output clock pins.

Cyclone II High-Speed I/O Interface

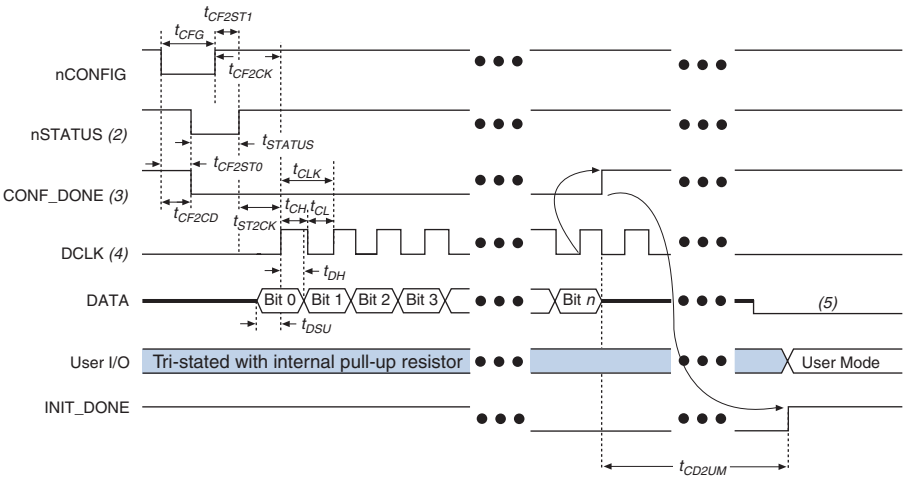
Cyclone II devices provide a multi-protocol interface that allows communication between a variety of I/O standards, including LVDS, LVPECL, RSDS, mini-LVDS, differential HSTL, and differential SSTL. This feature makes the Cyclone II device family ideal for applications that require multiple I/O standards, such as protocol translation.

PS Configuration Timing

A PS configuration must meet the setup and hold timing parameters and the maximum clock frequency. When using a microprocessor or another intelligent host to control the PS interface, ensure that you meet these timing requirements.

Figure 13–12 shows the timing waveform for PS configuration for Cyclone II devices.

Figure 13–12. PS Configuration Timing Waveform *Note (1)*



Notes to Figure 13–12:

(1) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS and CONF_DONE are at logic high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
(2) Upon power-up, the Cyclone II device holds nSTATUS low for the time of the POR delay.
(3) Upon power-up, before and during configuration, CONF_DONE is low.
(4) In user mode, drive DCLK either high or low when using the PS configuration scheme, whichever is more convenient. When using the AS configuration scheme, DCLK is a Cyclone II output pin and should not be driven externally.
(5) Do not leave the DATA pin floating after configuration. Drive it high or low, whichever is more convenient.

Table 13–11. Dedicated Configuration Pins on the Cyclone II Device (Part 2 of 5)

Pin Name	User Mode	Configuration Scheme	Pin Type	Description
nSTATUS	N/A	All	Bidirectional open-drain	The Cyclone II device drives nSTATUS low immediately after power-up and releases it after the POR time. This pin provides a status output and input for the Cyclone II device. If the Cyclone II device detects an error during configuration, it drives the nSTATUS pin low to stop configuration. If an external source (for example, another Cyclone II device) drives the nSTATUS pin low during configuration or initialization, the target device enters an error state. Driving nSTATUS low after configuration and initialization does not affect the configured device. If your design uses a configuration device, driving nSTATUS low causes the configuration device to attempt to configure the FPGA, but since the FPGA ignores transitions on nSTATUS in user mode, the FPGA does not reconfigure. To initiate a reconfiguration, pull the nCONFIG pin low. The enhanced configuration devices' and EPC2 devices' OE and nCS pins are connected to the Cyclone II device's nSTATUS and CONF_DONE pins, respectively, and have optional internal programmable pull-up resistors. If you use these internal pull-up resistors on the enhanced configuration device, do not use external 10-kΩ pull-up resistors on these pins. When using EPC2 devices, you should only use external 10-kΩ pull-up resistors. The input buffer on this pin supports hysteresis using Schmitt trigger circuitry.